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## Product Change Notification - GBNG-27AMWI895 (Printer Friendly)

**Date:**

31 Mar 2017

**Product Category:**

Linear Op Amps

**Notification subject:**

CCB 2889 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 120K wafer technology available in 8L TDFN package at NSEB assembly site.

**Notification text:**

**PCN Status:**

Initial notification.

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L TDFN package at NSEB assembly site.

**Pre Change:**

Assembled using gold (Au) bond wire.

**Post Change:**

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB	NSEB
<b>Wire material</b>	Au	CuPdAu
<b>Die attach material</b>	8200T	8600
<b>Molding compound material</b>	G770HCD	G700LTD

<b>Lead frame material</b>	C194	C194
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**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	March 2017					→	August 2017				
	09	10	11	12	13		31	32	33	34	35
Initial PCN Issue Date					X						
Qual Report Availability									X		
Final PCN Issue Date									X		

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**

**March 31, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_GBNG-27AMWI895\\_Affected CPN.pdf](#)

[PCN\\_GBNG-27AMWI895\\_Qual Plan.pdf](#)

[PCN\\_GBNG-27AMWI895\\_Affected CPN.xlsx](#)

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